

# Claims

- [c1] 1. A method of fabricating a flip chip ball grid array (FC-BGA) package, comprising:  
providing a substrate comprising a first surface and a second surface, wherein the first surface comprises a plurality of cavities;  
adhering a plurality of flip chips to the cavities of the substrate;  
filling an underfill material between the substrate and the flip chips;  
performing a ball placement step for attaching a plurality of solder balls to the second surface of the substrate;  
and  
singulating the substrate for separating portions of the substrate having the flip chips adhered thereon.
- [c2] 2. The method of claim 1, further comprising a glue sealing step for filling a sealing glue material into the cavities to cover the flip chips after the step of filling the underfill material.
- [c3] 3. The method of claim 1, wherein the step of providing the substrate comprises:  
providing a substrate core layer;

forming a circuit layer over the substrate core layer; and forming a plurality of openings in the substrate core layer to expose portions of the circuit layer.

- [c4] 4. The method of claim 3, wherein the circuit layer comprises a multi-layer structure comprising at least a dielectric layer and a plurality of conductive layers, wherein the dielectric layer is sandwiched between two of the conductive layers.
- [c5] 5. The method of claim 3, wherein a method of forming the openings comprises an etching method.
- [c6] 6. The method of claim 1, wherein the step of adhering a plurality of flip chips to the cavities comprises adhering each of the flip chips to each of the cavities respectively.
- [c7] 7. The method of claim 1, wherein the step of adhering a plurality of flip chips to the cavities comprises adhering more than one flip chips to each of the cavities respectively.